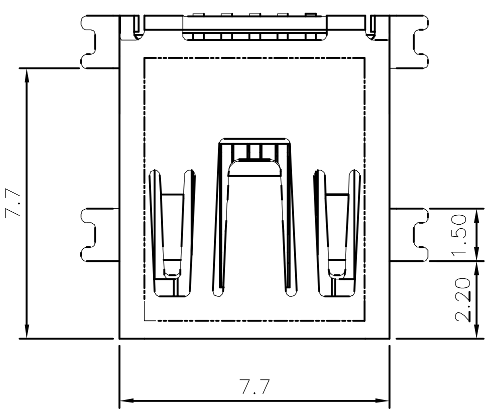
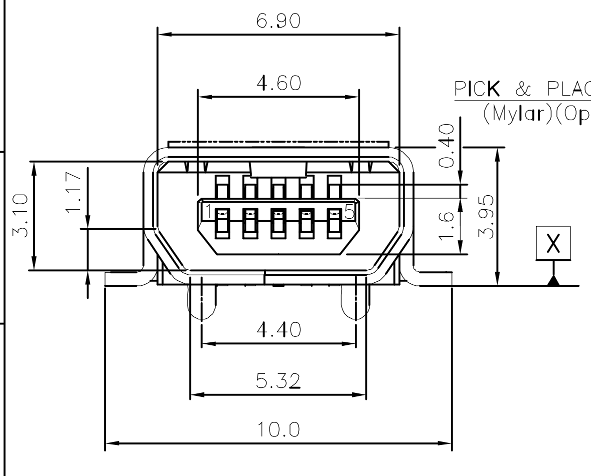
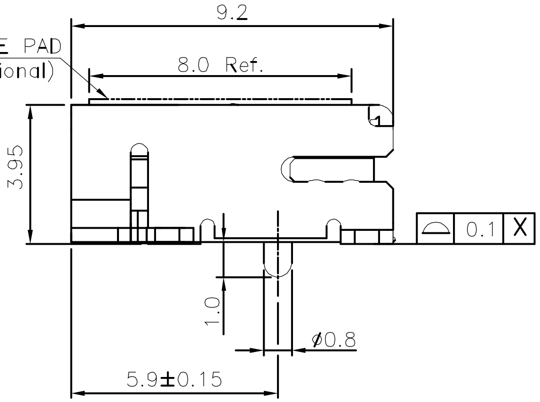
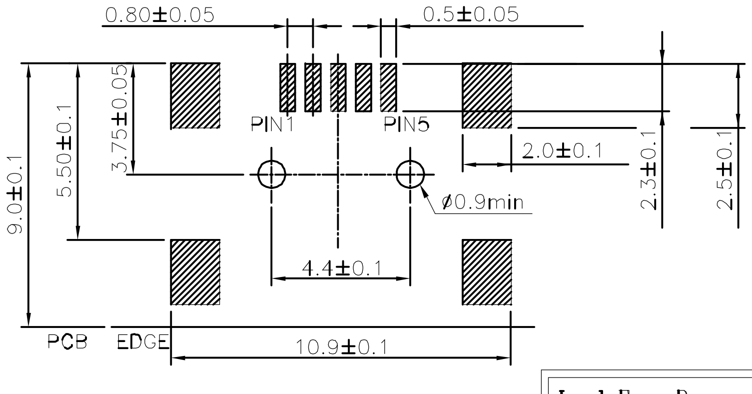


Materials :
- * Insulation: Glass filled Polyamide UL 94V–0
- * Contacts: Copper Alloy
- * Plating : Selective 0.76µm(30µ") Gold plated over 1.27µm(50µ") Nickel
- * Shell: Copper Alloy
- * Shell Plating: 120µ" Tin plated over 30µ" Nickel(Matte Tin Finish)
- * Pick & Place Pad : Glass filled polyamide UL 94V–0
- * Solder tail with Matte Tin Finish
- * Packing:Tape & Reel Packing (With Pick & Place Pad)



TYPE–AB





Recommended P.C. Board Layout

Lead Free Process

RoHS Compliant

TOLERANCE UNLESS OTHERWISE SPECIFIED	
.X ± 0.20/.008	.X° ± 1°
.XX ± 0.10/.004	.X° ±
.XXX ± 0.05/.002	.XX° ±

Id.	Modification	Date	Name
②	Update	29.07.08	N.Schulz
①	Neuanlage	12.12.06	Hellwig

	Date	Name
Drawn	12.12.06	Hellwig
Approved	11.06.08	Hellwig

ASSMANN
WSW Components

Customer - No.

Assmann - No
A-USB AB M5-SMD-C

Drawing-No.
ASS 1161 CO
rev02

Replace

Sheet